

IN THE CLAIMS:

Claim 2 was previously cancelled herein. Claim 6 has been amended herein. All of the pending claims 1 through 8 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously Presented) A method of attaching a semiconductor die to a lead frame comprising:  
providing a source of snap curable adhesive;  
providing a source of lead frames, each lead frame having an attaching surface;  
providing a source of semiconductor die, each semiconductor die having an active surface;  
heating at least one of the semiconductor die to a temperature capable of effecting snap-curing of the snap cure adhesive;  
applying said snap curable adhesive to portions of one of the lead frames; and  
pressing said active surface of one of the heated semiconductor die against said portions of one of the lead frames having said snap curable adhesive thereon, thereby deforming the adhesive.
2. (Canceled) The method of claim 1, further including heating said one of the semiconductor die.
3. (Original) The method of claim 1, wherein said snap curable adhesive includes a snap curable epoxy having a cure time of about one second.
4. (Original) The method of claim 1, wherein said snap curable adhesive includes an adhesive having a cure time of substantially one minute or less.

5. (Original) The method of claim 1, wherein said snap curable adhesive is applied to the portions of said one of the lead frames using a roller.

6. (Currently Amended) A method of attaching a semiconductor die to a lead frame comprising:

providing a source of snap curable adhesive;

providing a source of lead frames, each lead frame having an attaching surface;

providing a source of semiconductor die, each semiconductor die having an active surface;

applying said snap curable adhesive to portions of the active surface of one of the semiconductor ~~die~~die;

heating at least one of the semiconductor die to a temperature capable of effecting snap-curing of the snap cure adhesive; and

pressing said snap curable adhesive with portions of one of said lead frames such that said snap-cure adhesive is formed into a layer.

7. (Original) The method of claim 6, wherein said snap curable adhesive includes an adhesive having a curing time of about one second or less.

8. (Previously Presented) The method of claim 6, wherein said snap curable adhesive is applied to said active surface of said one of the semiconductor die in a predetermined pattern.

**IN THE DRAWINGS:**

The attached sheets of drawings include changes to FIGS. 1 and 4. These sheets, which include FIGS. 1, 2, 3, 4, and 5, replace the original sheets including FIGS. 1 and 4.

Specifically, FIG. 1 has been revised to change the reference numeral "268" to --168--; and FIG. 4 has been revised to change the reference numeral "170" to --172--. No new matter has been added.